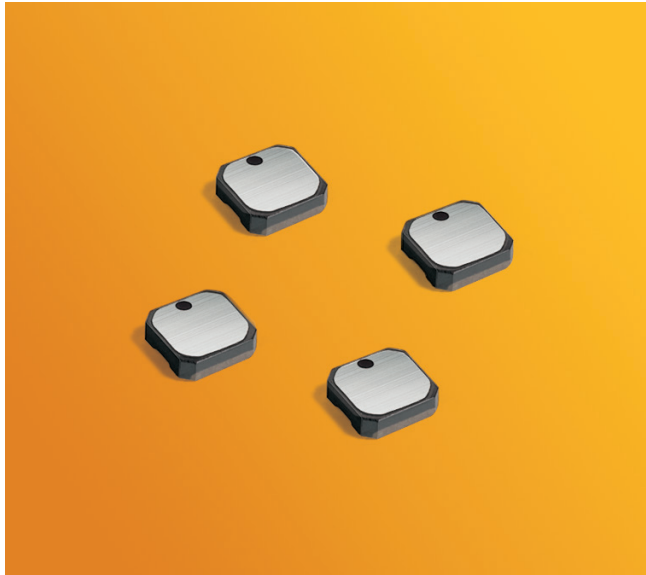


# High Reliability Power Inductors MS369PJB



- High temperature materials allow operation in ambient temperatures up to 155°C
- Special construction allows it to pass vibration testing to 80 G and shock testing to 1000 G.
- Tin-lead (Sn-Pb) termination for the best possible board adhesion

**Core material** Ferrite

**Terminations** Tin-lead (63/37) over tin over nickel.

**Weight** 27 – 32 mg

**Ambient temperature** –55°C to +105°C with (40°C) Irms current

**Maximum part temperature** +155°C (Ambient + temperature rise)

**Storage temperature** Component: –55°C to +155°C.

Tape and reel packaging: –55°C to +80°C

**Resistance to soldering heat** Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

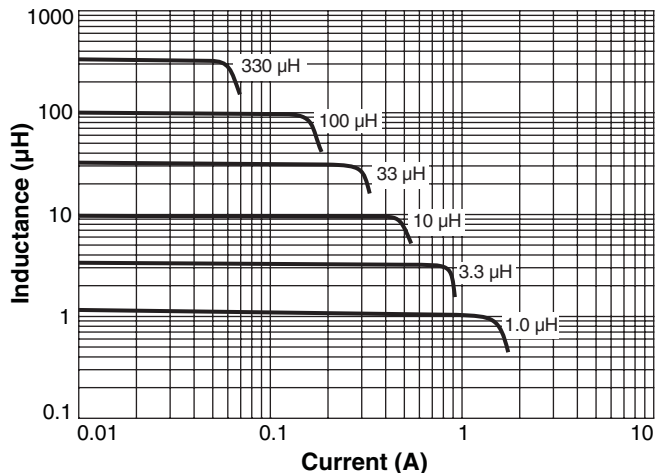
**Moisture Sensitivity Level (MSL)** 1 (unlimited floor life at <30°C / 85% relative humidity)

**Enhanced crush-resistant packaging** 1000/7" reel

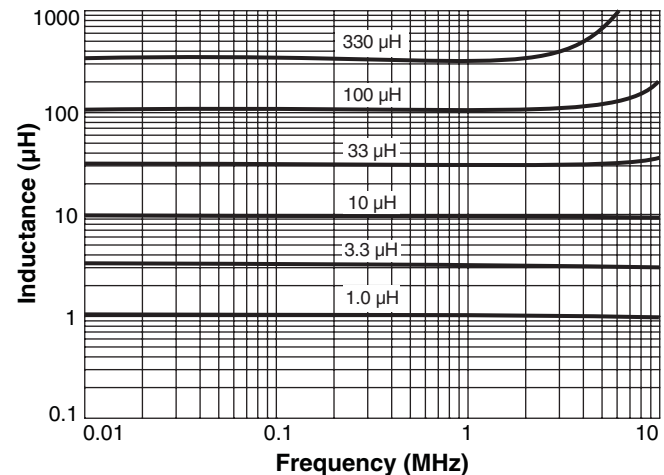
Plastic tape: 12 mm wide, 0.23 mm thick, 8 mm pocket spacing, 1.37 mm pocket depth

**Recommended pick and place nozzle** OD: 3 mm; ID: ≤1.5 mm

## Typical L vs Current



## Typical L vs Frequency



# MS369PJB Series (3008)

Part number <sup>1</sup>	Inductance <sup>2</sup> ±20% (μH)	DCR max <sup>3</sup> (Ohms)	SRF (MHz) <sup>4</sup>		Isat (A) <sup>5</sup>			Irms (A) <sup>6</sup>	
			min	typ	10% drop	20% drop	30% drop	20°C rise	40°C rise
MS369PJB561MSZ	0.56	0.072	231	330	1.8	2.0	2.1	1.1	1.6
MS369PJB801MSZ	0.80	0.092	178	255	1.6	1.7	1.8	0.88	1.3
MS369PJB102MSZ	1.0	0.125	154	220	1.3	1.4	1.5	0.72	1.0
MS369PJB152MSZ	1.5	0.134	119	170	1.1	1.3	1.3	0.70	0.96
MS369PJB222MSZ	2.2	0.175	105	150	1.0	1.1	1.1	0.68	0.88
MS369PJB332MSZ	3.3	0.285	79.8	114	0.81	0.86	0.88	0.59	0.76
MS369PJB472MSZ	4.7	0.350	60.9	87	0.68	0.73	0.74	0.54	0.64
MS369PJB562MSZ	5.6	0.450	54.6	78	0.62	0.67	0.70	0.46	0.58
MS369PJB682MSZ	6.8	0.500	52.5	75	0.58	0.61	0.63	0.40	0.54
MS369PJB822MSZ	8.2	0.600	42.7	61	0.52	0.56	0.58	0.36	0.48
MS369PJB103MSZ	10	0.650	39.2	56	0.46	0.51	0.52	0.34	0.45
MS369PJB123MSZ	12	0.790	34.3	49	0.45	0.48	0.50	0.30	0.40
MS369PJB183MSZ	18	1.25	26.6	38	0.35	0.38	0.40	0.26	0.35
MS369PJB223MSZ	22	1.50	24.5	35	0.29	0.33	0.34	0.23	0.30
MS369PJB333MSZ	33	2.30	16.1	23	0.27	0.30	0.31	0.20	0.26
MS369PJB473MSZ	47	3.00	14.7	21	0.22	0.23	0.24	0.17	0.22
MS369PJB683MSZ	68	4.75	12.6	18	0.18	0.19	0.20	0.14	0.18
MS369PJB104MSZ	100	6.85	9.8	14	0.15	0.16	0.16	0.13	0.17
MS369PJB124MSZ	120	7.00	9.1	13	0.084	0.094	0.10	0.11	0.15
MS369PJB154MSZ	150	8.00	7.7	11	0.080	0.088	0.092	0.10	0.14
MS369PJB184MSZ	180	9.00	7.0	10	0.070	0.078	0.082	0.10	0.13
MS369PJB224MSZ	220	11.50	6.3	9	0.067	0.073	0.076	0.080	0.12
MS369PJB334MSZ	330	18.00	4.9	7	0.059	0.064	0.066	0.070	0.10

1. When ordering, please specify **screening** code:

**MS369PJB104MSZ**

**Screening:** Z = Unscreened

Y = Unscreened (SLDC Option A)

W = Unscreened (SLDC Option B)

H = Coilcraft CP-SA-10001 Group A

G = Coilcraft CP-SA-10001 Group A (SLDC Option A)

D = Coilcraft CP-SA-10001 Group A (SLDC Option B)

1 = EEE-INST-002 (Family 1) Level 1

2 = EEE-INST-002 (Family 1) Level 2

3 = EEE-INST-002 (Family 1) Level 3

4 = MIL-STD-981 (Family 04) Class B

5 = MIL-STD-981 (Family 04) Class S

F = ESCC3201 (F4 operational life performed at 105°C)

- Screening performed to the document's latest revision.
- Lot qualification (Group B) available.
- Testing T and U have been replaced with more detailed codes 4, 5, and 1, 2, 3, respectively. Codes T and U can still be used, if necessary. Custom testing also available.
- Country of origin restrictions available; prefix options G or F.

2. Inductance tested at 100 kHz, 0.1 Vrms using an Agilent/HP 4192A or equivalent.

3. DCR measured on a micro-ohmmeter.

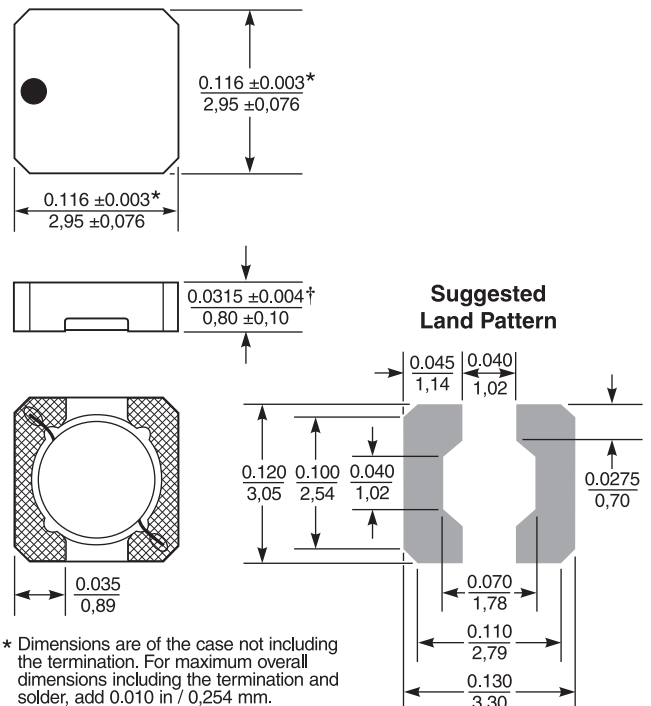
4. SRF measured using an Agilent/HP 8753ES or equivalent.

5. DC current that causes the specified inductance drop from its value without current.

6. Current that causes the specified temperature rise from 25°C ambient. This information is for reference only and does not represent absolute maximum ratings.

7. Electrical specifications at 25°C.

Refer to Doc 362 "Soldering Surface Mount Components" before soldering.



\* Dimensions are of the case not including the termination. For maximum overall dimensions including the termination and solder, add 0.010 in / 0.254 mm.

† Height dimension is after mounting. For maximum height dimension before mounting, add 0.006 in / 0.152 mm.

Dimensions are in  $\frac{\text{inches}}{\text{mm}}$